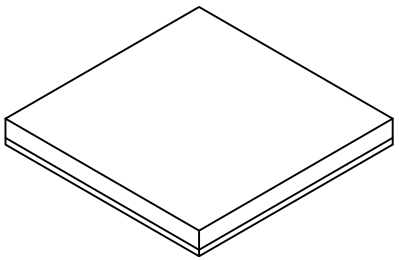
RGUER,09/11/00,15:58:42,QPackage,Version: Released13 GREME,02/06/02,11:47:49,DCL27Q

REVISION HISTORY					
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	C06648	INITIAL RELEASE	RGUER	LMACK	09/02/99
01	C10133	ADDED 80 AND 84 MATRICES	RGUER	DARNO	09/15/00
02	C14958	ADDED 128 BALL FOOTPRINT	GREME	GREME	02/05/02



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 144.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 12 X 12.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.50mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL X.X ±0.1, X.XX ±0.05, X.XXX ±0.030
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994
MATERIAL: N/A
FINISH: N/A
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED: RGUER	07/30/99
CHECKED: JMICKS	07/30/99
PRODUCT MANAGER: TPANC	07/30/99
RELEASED: DSCHU	09/02/99

Amkor Technology, Inc. Chandler, Arizona, USA
Anam Semiconductor, Inc., Seoul, Korea
Amkor Technology Philippines, Inc. Manila, Philippines

TITLE: PACKAGE OUTLINE - MAF, 12 X 12 MATRIX, 7.00mm X 7.00mm X 1.00mm, 0.60mm MOLD CAP, 0.30mm BALL, 0.50mm PITCH, LAMINATE SUBSTRATE, AAWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	75430	02

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 4

FORM NO: MBFLAM1C1.DWG